

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

1. (original) Smart card having a card body (11), at least one recess (12a, 12b) arranged therein for receiving at least one chip module (16) having module connections (17) in the edge region (16a) of the chip module (16) and a conductive structure body embedded in the card body (11) and having body contact connections (13), in particular an antenna having antenna connections which are arranged below the edge region (16a) of the chip module (16), characterized in that, with the chip module (16) installed between the module connections (17) on the one hand and the body contact connections (13) on the other hand, adhesive parts (14) applied at points and made of elastic, conductive material are arranged between the connections (13, 17) with pressure being applied to produce a contact.
2. (original) Smart card according to Claim 1, characterized in that the adhesive parts (14) are arranged within cutouts (15) which are arranged in the card body (11) below the edge region (16a) of the chip module (16) and at the bottom terminate with the body contact connections (13).
3. (original) Smart card according to Claim 2, characterized in that the cutouts (15) have a volume size that is sufficient to completely receive the adhesive parts (14) under the application of pressure.
4. (currently amended) Smart card according to Claim 2 or 3, characterized in that in the direction of the card body thickness the cutouts (15) have height dimensions (14b) that are smaller than the height (14, 14b) of the adhesive parts (14) applied at points, without the application of pressure.
5. (currently amended) Smart card according to ~~any of the preceding claims~~ Claim 1, characterized in that the adhesive parts (14) made of elastic material are cured prior to installation of the chip module (11) in order to produce a permanent contact between the chip

module connections (13) and body contact connections (17) following installation of the chip module (11) as a resilient buffer.

6. (currently amended) Smart card according to ~~any of the preceding claims~~ Claim 1, characterized in that the adhesive parts (14) primarily act along the card body thickness as a resilient buffer.

7. (original) Method of producing smart cards having a card body (11), at least one recess (12a, 12b) arranged therein for receiving at least one chip module (16) having module connections (17) in the edge region (16a) of the chip module (16) and a conductive structure body embedded in the card body (11) and having body contact connections (13), in particular an antenna connections which are arranged below the edge region (16a) of the chip module (16), characterized in that, prior to installation of the chip module (11), adhesive parts (14) made of elastic, conductive material are applied to the body contact connections (13) and/or the module connections (17) and cured, and then the chip module (11) is installed in the card body (11) with pressure being applied to the adhesive parts (14) made of elastic material.

8. (original) Method according to Claim 7, characterized in that, prior to installation of the chip module (11), the adhesive parts (14) are applied so as to be about 0.05 to 0.15 mm higher than upper edge regions (15a) of cutouts (15) arranged in the card body, which cutouts are designed to receive the adhesive parts (14).